

Single P-channel MOSFET

ELM13407CA-S

■ General description

ELM13407CA-S uses advanced trench technology to provide excellent $R_{ds(on)}$, low gate charge and low gate resistance.

■ Features

- $V_{ds} = -30V$
- $I_d = -4.1A$ ($V_{gs} = -10V$)
- $R_{ds(on)} < 52m\Omega$ ($V_{gs} = -10V$)
- $R_{ds(on)} < 87m\Omega$ ($V_{gs} = -4.5V$)

■ Maximum absolute ratings

Parameter	Symbol	Limit	Unit	Note
Drain-source voltage	V_{ds}	-30	V	
Gate-source voltage	V_{gs}	± 20	V	
Continuous drain current	I_d	-4.1	A	1
Ta=70°C		-3.5		
Pulsed drain current	I_{dm}	-20	A	2
Power dissipation	P_d	1.4	W	1
Ta=70°C		1.0		
Junction and storage temperature range	T_j, T_{stg}	-55 to 150	°C	

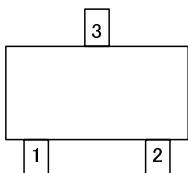
■ Thermal characteristics

Parameter		Symbol	Typ.	Max.	Unit	Note
Maximum junction-to-ambient	t≤10s	$R_{\theta ja}$	65	90	°C/W	1
Maximum junction-to-ambient	Steady-state		85	125	°C/W	
Maximum junction-to-lead	Steady-state	$R_{\theta jl}$	43	60	°C/W	3

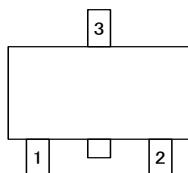
■ Pin configuration

■ Circuit

SOT-23 (TOP VIEW)

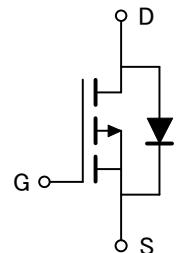


(Without extra bar)



(With extra bar)

Pin No.	Pin name
1	GATE
2	SOURCE
3	DRAIN



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■ Electrical characteristics

$T_a=25^\circ C$

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
STATIC PARAMETERS						
Drain-source breakdown voltage	BVdss	$Id=-250\ \mu A, Vgs=0V$	-30			V
Zero gate voltage drain current	Idss	Vds=-24V			-1	μA
		Vgs=0V	Tj=55°C		-5	
Gate-body leakage current	Igss	Vds=0V, Vgs=±20V			±100	nA
Gate threshold voltage	Vgs(th)	Vds=Vgs, Id=-250 μA	-1.0	-1.8	-3.0	V
On state drain current	Id(on)	Vgs=-4.5V, Vds=-5V	-10			A
Static drain-source on-resistance	Rds(on)	Vgs=-10V		40.5	52.0	$m\Omega$
		Id=-4.1A	Tj=125°C	57.0	73.0	
		Vgs=-4.5V, Id=-3A		64.0	87.0	
Forward transconductance	Gfs	Vds=-5V, Id=-4A	5.5	8.2		S
Diode forward voltage	Vsd	Is=-1A, Vgs=0V		-0.77	-1.00	V
Max. body-diode continuous current	Is				-2.2	A
DYNAMIC PARAMETERS						
Input capacitance	Ciss	Vgs=0V, Vds=-15V, f=1MHz		700	840	pF
Output capacitance	Coss			120		pF
Reverse transfer capacitance	Crss			75		pF
Gate resistance	Rg	Vgs=0V, Vds=0V, f=1MHz		10	15	Ω
SWITCHING PARAMETERS						
Total gate charge (10V)	Qg	Vgs=-4.5V, Vds=-15V Id=-4A		14.3	18.0	nC
Total gate charge (4.5V)	Qg			7.0		nC
Gate-source charge	Qgs			3.1		nC
Gate-drain charge	Qgd			3.0		nC
Turn-on delay time	td(on)	Vgs=-10V, Vds=-15V RL=3.6 Ω , Rgen=3 Ω		8.6		ns
Turn-on rise time	tr			5.0		ns
Turn-off delay time	td(off)			28.2		ns
Turn-off fall time	tf			13.5		ns
Body diode reverse recovery time	trr	If=-4A, dl/dt=100A/ μs		27	36	ns
Body diode reverse recovery charge	Qrr			15		nC

NOTE :

1. The value of $R_{\theta ja}$ is measured with the device mounted on 1in² FR-4 board of 2oz. Copper, in still air environment with $T_a=25^\circ C$. The value in any given applications depends on the user's specific board design, The current rating is based on the $t \leq 10s$ thermal resistance rating.
2. Repetitive rating, pulse width limited by junction temperature.
3. The $R_{\theta ja}$ is the sum of the thermal impedance from junction to lead $R_{\theta jl}$ and lead to ambient.
4. The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5%max.
5. These tests are performed with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_a=25^\circ C$. The SOA curve provides a single pulse rating.

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■ Typical electrical and thermal characteristics

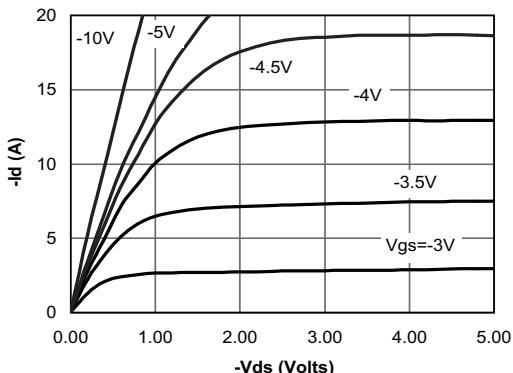


Figure 1: On-Region Characteristics

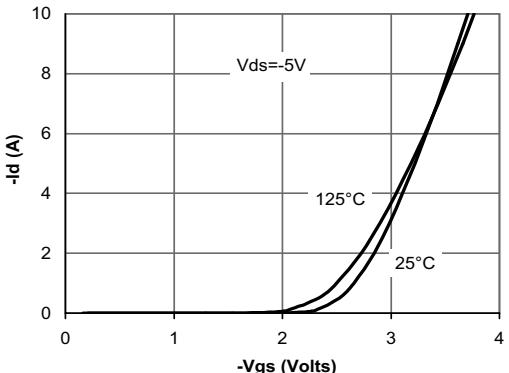


Figure 2: Transfer Characteristics

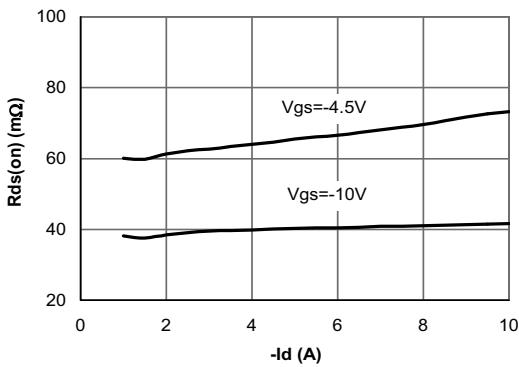


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

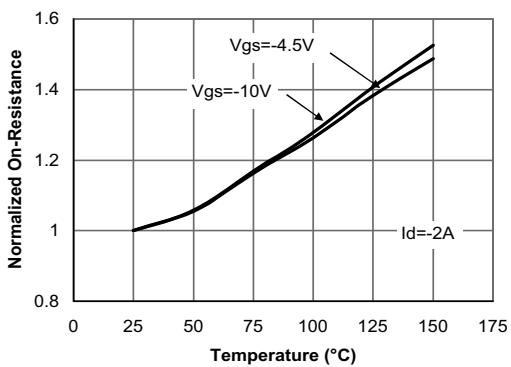


Figure 4: On-Resistance vs. Junction Temperature

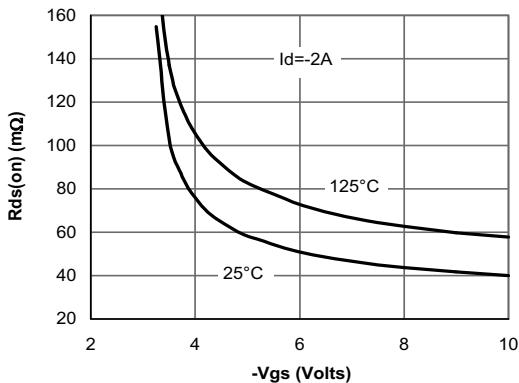


Figure 5: On-Resistance vs. Gate-Source Voltage

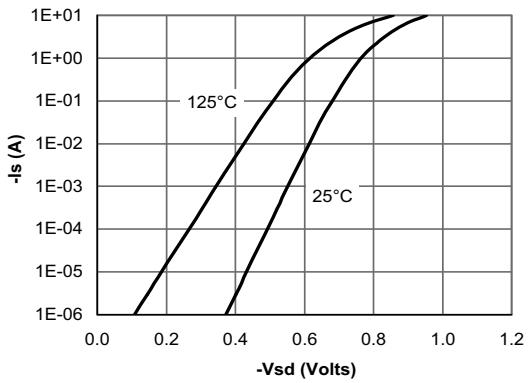


Figure 6: Body-Diode Characteristics

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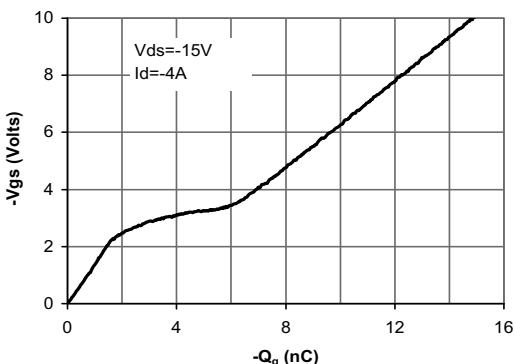


Figure 7: Gate-Charge Characteristics

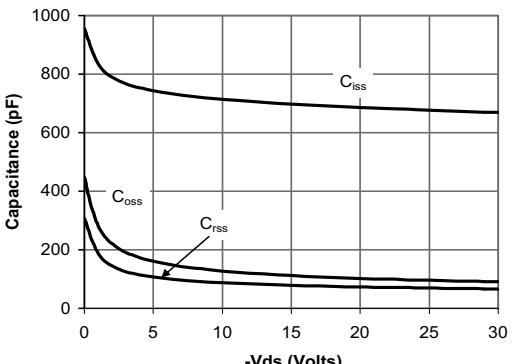


Figure 8: Capacitance Characteristics

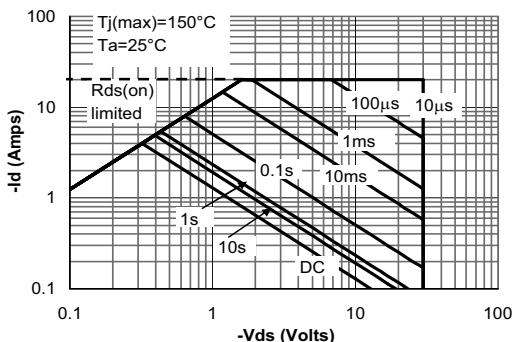


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

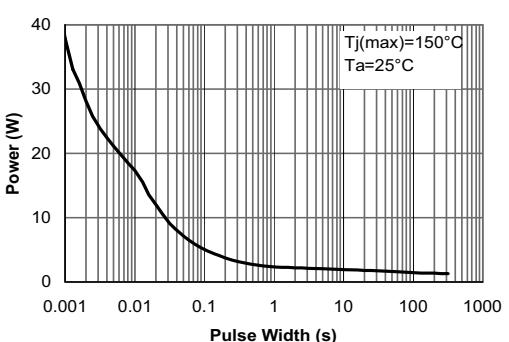


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

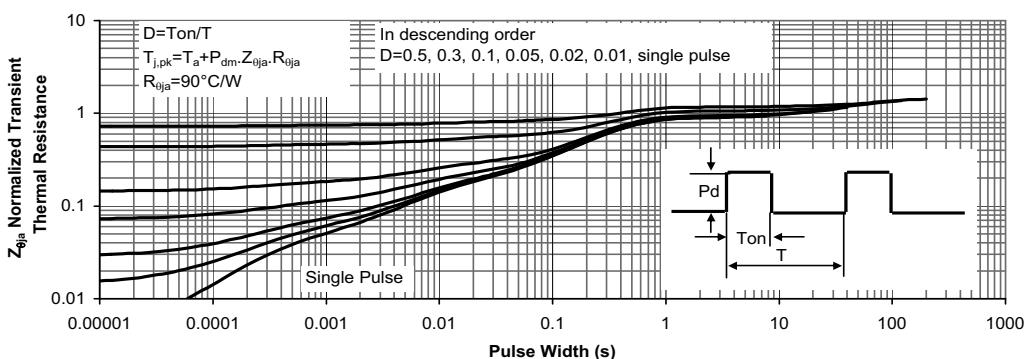


Figure 11: Normalized Maximum Transient Thermal Impedance